

Automotive 6-axis MotionTracking® MEMS Device for ADAS and Autonomous Driving Applications

GENERAL DESCRIPTION

The IAM-20685HP is a 6-axis MotionTracking device that combines a 3-axis gyroscope and a 3-axis accelerometer in a small plastic package with wettable flanks option. By leveraging its patented and volume-proven CMOS-MEMS fabrication platform, TDK InvenSense has driven the package size down to a footprint and thickness of 4.5x4.5x1.1 mm³ (24-pin DQFN), to offer fully integrated, high performance component in a compact form factor.

The IAM-20685HP features:

- Six independent mechanical structures
- Gyroscope with programmable full scale range from ±41 dps to ±1966 dps
- Accelerometer with programmable full-scale range from ±2g, to ±65g
- Minimal cross-axis sensitivity between the accelerometer and gyroscope axes
- 10,000 g shock tolerant structure
- Two temperature sensors
- 10 MHz, 32-bits Serial Peripheral Interface (SPI) with CRC-based error-detecting code algorithm
- ISO26262:2018 ASIL B
- Automotive-qualified
- Reliability testing performed according to Automotive Electronics Council AEC – Q100 grade 1 (-40°C to 125°C) qualification requirements
- Final test over temperature at: -40°C, 25°C, 125°C

IAM-20685HP includes on-chip 16-bit ADCs, programmable digital filters, and embedded self-test. The device features VDD operating range of 3.0V to 5.5V, separate digital IO supply VDDIO from 3.0V to 5.5V, and current consumption below 10 mA in all operating conditions. The IAM-20685HP has been developed according to ISO-26262:2018 as a Safety Element out of Context (SEoC) to address systems with automotive safety integrity level ASIL-B. Fault detection over lifetime is achieved by a set of 20 embedded safety mechanisms (SMs) executed either at startup, upon command, or in a continuous manner. Safety Manual is available upon request.

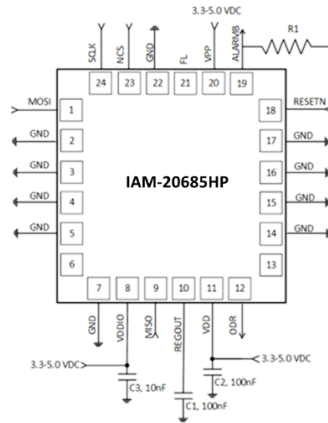
APPLICATIONS

IAM-20685HP addresses a wide range of Automotive applications, including but not limited to:

- Navigation
- Telematics and V2X

- Autonomous Driving
- Automated parking
- ADAS
- Dead Reckoning
- High precision positioning
- Vision system image stabilization

TYPICAL OPERATING CIRCUIT



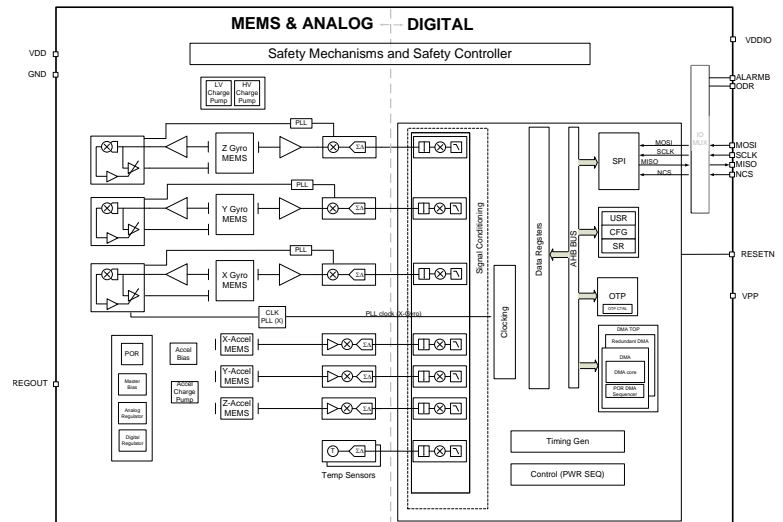
ORDERING INFORMATION

PART NUMBER†	TEMPERATURE	PACKAGE	MSL*
IAM-20685HP	-40°C to +125°C	24-Pin DQFN	3

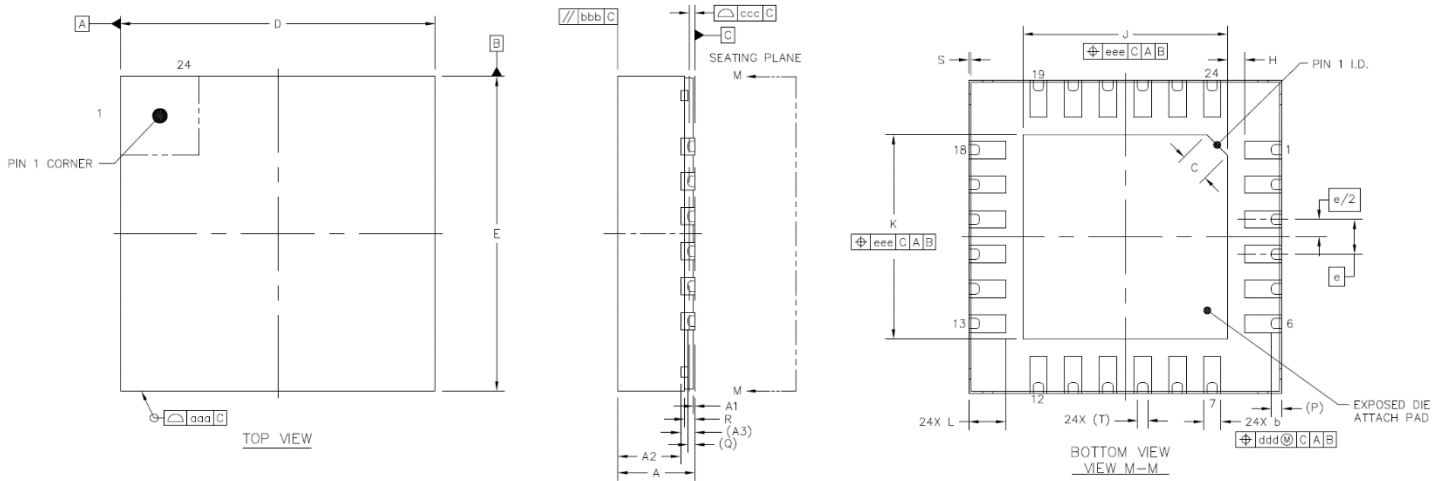
†Denotes RoHS and Green-compliant package

* Moisture sensitivity level of the package

BLOCK DIAGRAM



PACKAGE DIMENSIONS



	SYMBOL	MIN	NOM	MAX	
TOTAL THICKNESS	A	1.05	1.1	1.15	
STAND OFF	A1	0	0.02	0.05	
MOLD THICKNESS	A2	---	0.9	---	
L/F THICKNESS	A3	0.203 REF			
LEAD WIDTH	b	0.18	0.25	0.3	
BODY SIZE	X	D	4.4	4.5	4.6
	Y	E	4.4	4.5	4.6
LEAD PITCH	e	0.5 BSC			
EP SIZE	X	J	2.89	2.94	2.99
	Y	K	2.89	2.94	2.99
LEAD LENGTH	L	0.48	0.53	0.58	
	C	0.374	0.424	0.474	
	H	0.2	0.25	0.3	
MOLD FLATNESS	bbb	0.1			
COPLANARITY	ccc	0.08			
LEAD OFFSET	ddd	0.1			
EXPOSED PAD OFFSET	eee	0.1			
	fff	0.05			
HALF-CUT DEPTH	R	0.11	0.15	0.2	
HALF-CUT WIDTH	S	0.001	0.015	0.03	
WETTABLE DIMPLE WIDTH	T	0.1	0.15	0.2	
WETTABLE DIMPLE LENGTH	P	0.05	0.15	0.25	
WETTABLE DIMPLE DEPTH	Q	0.05	0.1	0.15	

REVISION HISTORY

REVISION DATE	REVISION	DESCRIPTION
09/24/2024	1.0	Initial release

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